## Device Material Content

### Package: 672 fBGA

#### Assembly: ASEM
- Size (mm): 27 x 27
- Lead pitch (mm): 1.0
- MSL: 3
- Reflow max (ºC): 250

#### Package Code: FN672

#### LAE3

<table>
<thead>
<tr>
<th>Materials</th>
<th>Weight (g)</th>
<th>% of Total Pkg. Wt.</th>
<th>% of Total Pkg. Wt.</th>
<th>Substance</th>
<th>CAS #</th>
<th>% of Subst.</th>
</tr>
</thead>
<tbody>
<tr>
<td>Die</td>
<td>0.0489</td>
<td>1.48%</td>
<td>1.48%</td>
<td>Silicon chip</td>
<td>7440-21-3</td>
<td>100.00%</td>
</tr>
<tr>
<td>Mold Compound</td>
<td>1.2119</td>
<td>36.73%</td>
<td>36.73%</td>
<td>Epoxy Resin</td>
<td>-</td>
<td>5.00%</td>
</tr>
<tr>
<td>D/A Epoxy</td>
<td>0.0069</td>
<td>0.21%</td>
<td>0.21%</td>
<td>Silver</td>
<td>7440-22-4</td>
<td>80.00%</td>
</tr>
<tr>
<td>Wire</td>
<td>0.0198</td>
<td>0.60%</td>
<td>0.59%</td>
<td>Gold (Au)</td>
<td>7440-57-5</td>
<td>98.50%</td>
</tr>
<tr>
<td>Solder Balls</td>
<td>0.6563</td>
<td>19.89%</td>
<td>19.19%</td>
<td>Tin (Sn)</td>
<td>7440-31-5</td>
<td>96.50%</td>
</tr>
<tr>
<td>Substrate</td>
<td>1.3563</td>
<td>41.10%</td>
<td>24.25%</td>
<td>Laminate*</td>
<td>-</td>
<td>59.00%</td>
</tr>
</tbody>
</table>

### Notes:
- * 0.24% max. concentration of Bisphenol A (CAS# 80-05-7) in substrate laminate material as impurity - not intentionally added.
- Constituent substances and proportions in epoxy materials are before curing.
- The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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April, 2018

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PCN:005A-17
Rev. C1